



The following is an index of Cypress Package Diagrams.
Click on the appropriate package letter to view package diagrams under that description.

TQFP	Thin Quad Flat Packs	A
PPGA	Plastic Pin Grid Arrays	B
Mini-BGA	Mini Ball Grid Array	BA
Thin BGA	Thin Ball Grid Array	BB
BGA	Ball Grid Array	BG
L2BGA	L2 Ball Grid Array	BL
CerDIP	Ceramic Dual-In-Line Packages	D
CQFP	Ceramic Flatpacks	F
CerSOJ	Ceramic Small Outline J-Bend	FJ
CPGA	Ceramic Pin Grid Arrays	G
WLCC	Ceramic Windowed J-Leaded Chip Carriers	H
PLCC	Plastic Leaded Chip Carriers	J
CerPACK	Cerpacks	K
LCC	Ceramic Leadless Chip Carriers	L
PQFP	Plastic Quad Flatpacks	N
SSOP	Shrunk Small Outline Packages	O
PDIP	Plastic Dual-In-Line Packages	P
QSOP	Quarter Size Outline Packages	Q
W-LCC	Ceramic Windowed Leadless Chip Carriers	Q
WPGA	Ceramic Windowed Pin Grid Arrays	R
SOIC	Plastic Small Outline ICs	S
SNC	Narrow SOIC	SN
W-CerPACK	Windowed Cerpacks	T
CQFP	Ceramic Quad Flatpacks	U
SOJ	Plastic Small Outline J-Bend	V
W-CerDIP	Ceramic Windowed Dual-In-Line Packages	W
CLCC	Ceramic J-Leaded Chip Carriers	Y
TSOP	Thin Small Outline Packages	Z
STSOP	Shrunk Thin Small Outline Packages	ZA
RTSOP	Reverse Thin Small Outline Packages	ZR
TSOP II	Thin Small Outline Packages, Type II	ZS
RTSOP II	Reverse Thin Small Outline Package, Type II	ZU
	Module Packages	